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INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(Use as many sheets as necessary)</i>		<i>Complete if Known</i>	
		Application Number	10/607,738
		Filing Date	June 26, 2003
		First Named Inventor	Houle, Sabina
		Group Art Unit	1725
		Examiner Name	Kiley Stoner
Sheet 1 of 1		Attorney Docket No: 884.832US1	

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EXAMINER

Kiley Stoner

DATE CONSIDERED 5/18/05